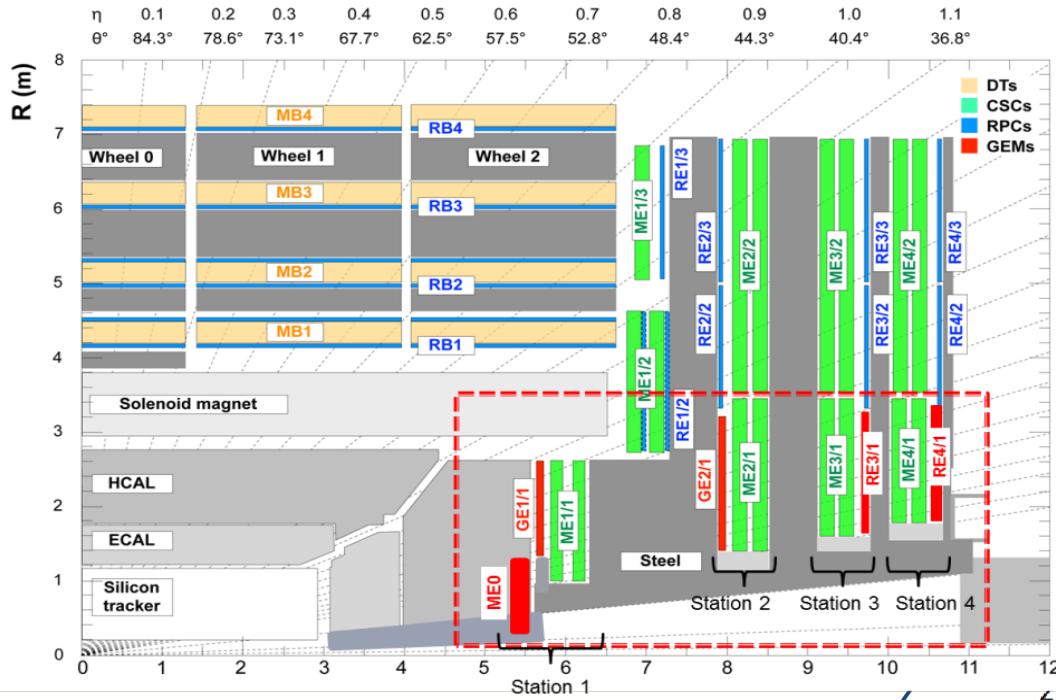


CMS GEMs – Electronics



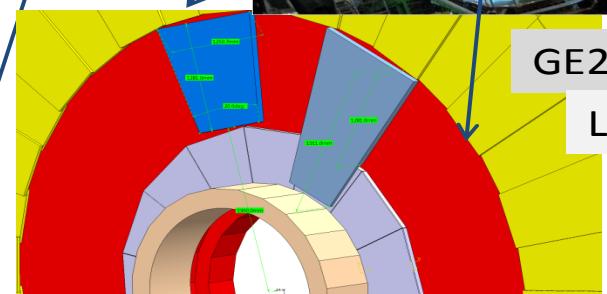
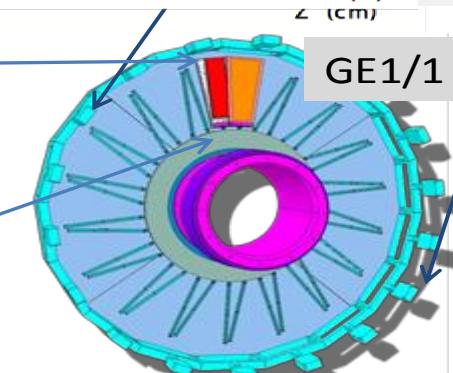
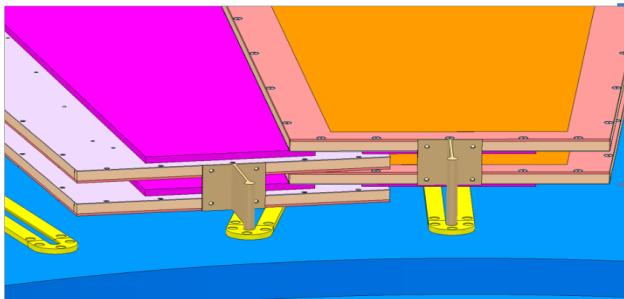
Introduction: the CMS GEM Endcap system



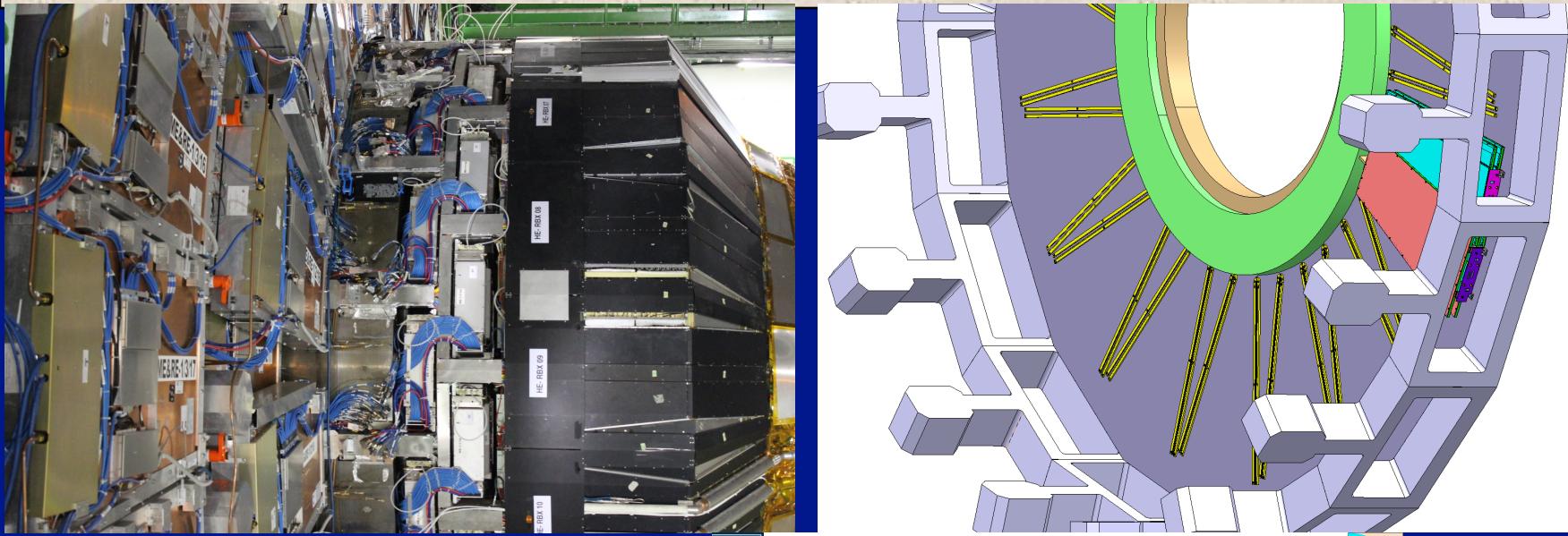
LS2

GE1/1

GE2/1
LS3?

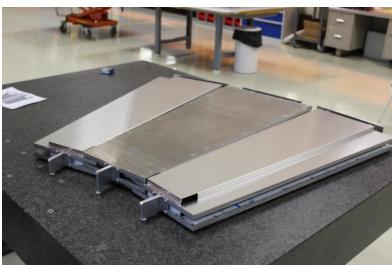


Installation Details : Detector Installation

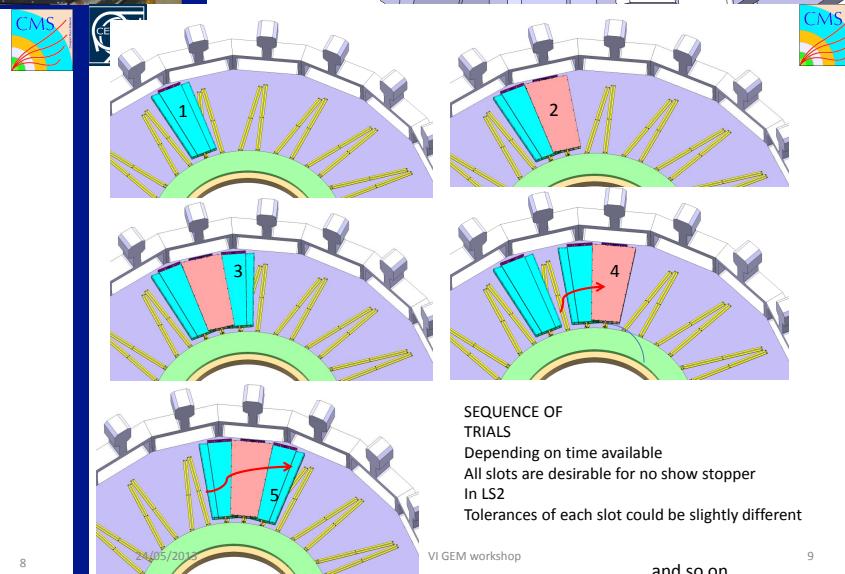


GE1/1 Dummies

"Mounted" on the marble table



Excellent overlap. With 3mm clearance from each side.



SEQUENCE OF TRIALS

Depending on time available
All slots are desirable for no show stopper
In LS2
Tolerances of each slot could be slightly different

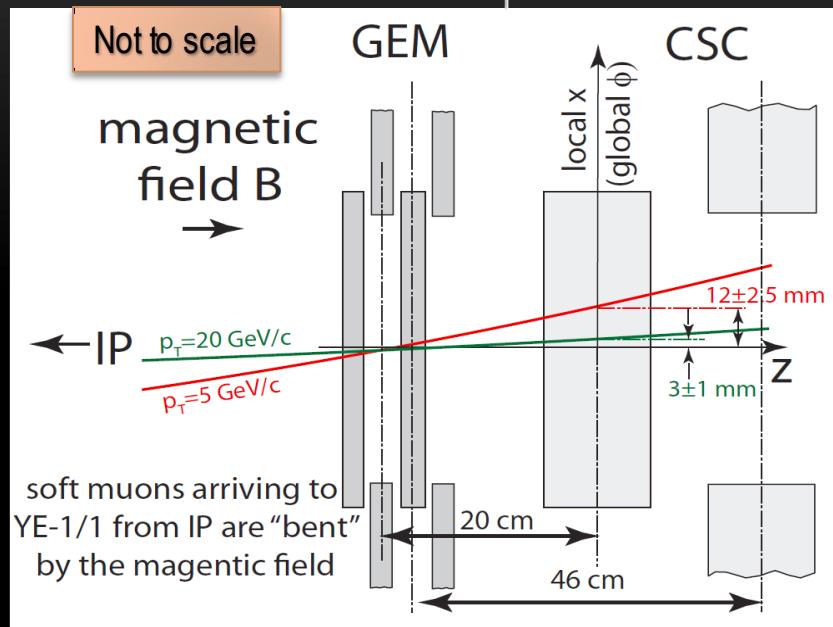
and so on...

A. Marinov
A. Conde Garcia

A NEW KNOB: GEM-CSC “BENDING ANGLE”

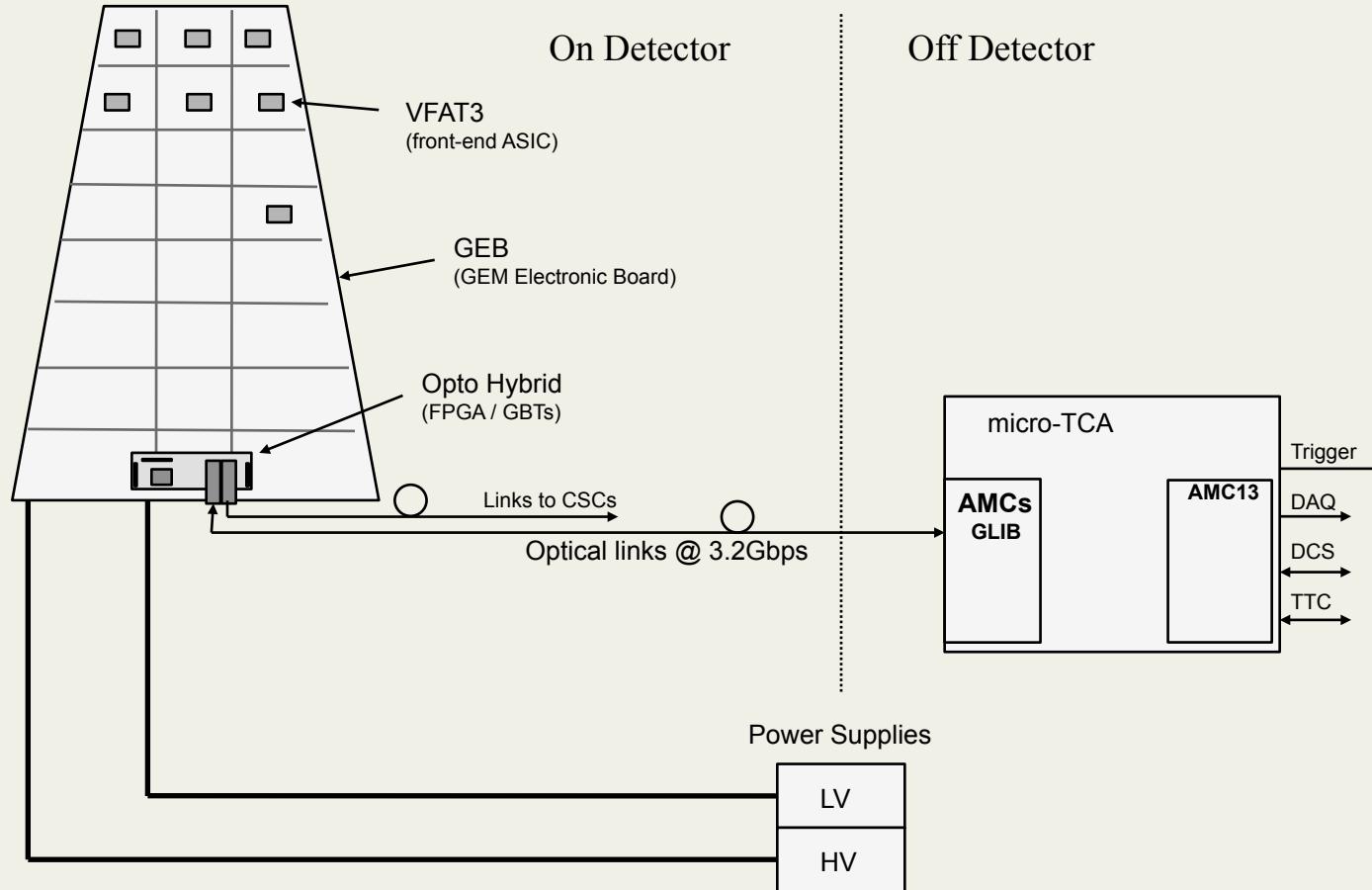
View from the top of the CMS down

- L1 muon momentum resolution can be improved with a second detector:
 - Inner tracker tracks at L1 – best solution, but not available until LS3
- A second muon system could improve momentum resolution if one can measure the “bending angle”
 - Used in the Barrel; CSCs are too thin (~ 11 cm) to see the bend
- A new detector in YE-1/1 (the least affected by scattering, largest B)
 - Increase “lever arm” from 10 cm to $\Delta z=30-50$ cm (physical constraints)
 - Need ~ 2 mm or better trigger resolution to effectively discriminate 5 GeV muons from 20+ GeV ones

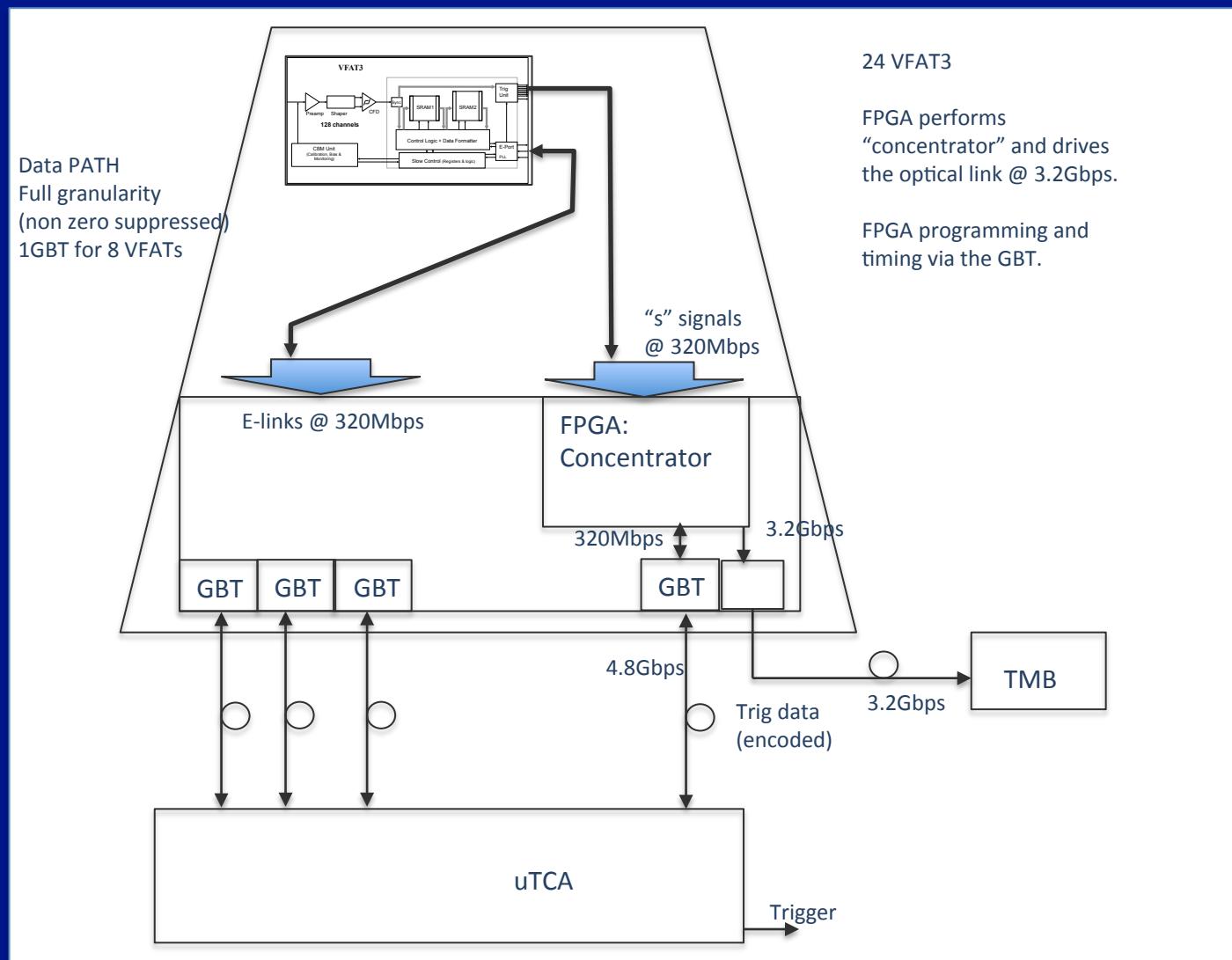


YE-1/1	$p_T=5$ GeV	$p_T=20$ GeV
$\Delta x_{\Delta z=30 \text{ cm}}$	$12 \pm 3 \text{ mm}$	$3 \pm 1 \text{ mm}$

CMS GEM Electronics System



The Electronics System



The Electronics System

VFAT3 : ASIC design by
CERN, CEA Saclay, INFN
Bari,

Data PATH
Full granularity
(non zero suppressed)
1GBT for 8 VFATs

VFAT2 & 3 Hybrids + GEB
(GEM Electronic Board)
Lappeenranta (LUT)

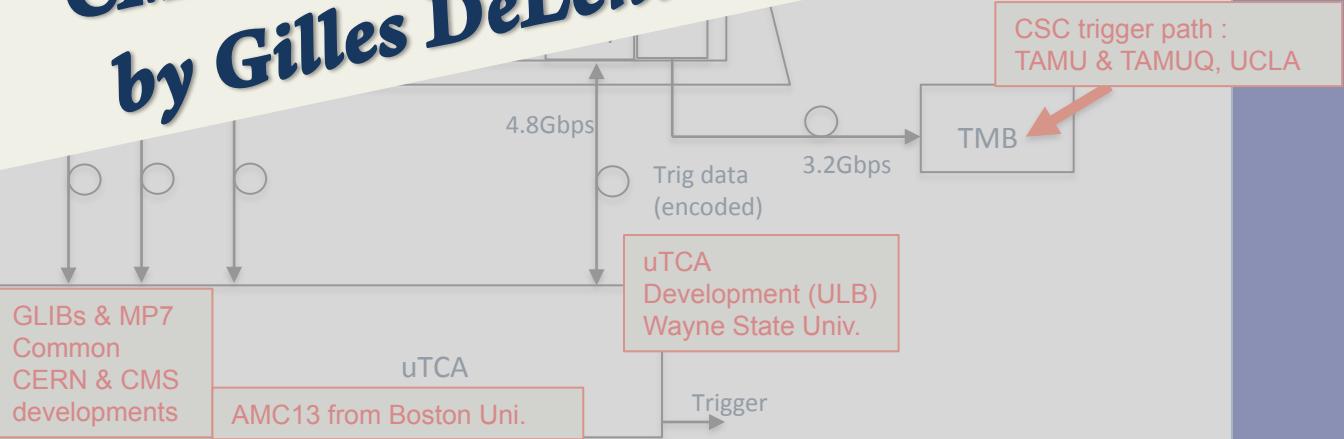
FPGA performs
“concentrator” and drives
the optical link @ 3.2Gbps.

FPGA programmi
time

*DAQ system covered in talk
“CMS Muon for HL-LHC”
by Gilles DeLentdecker*

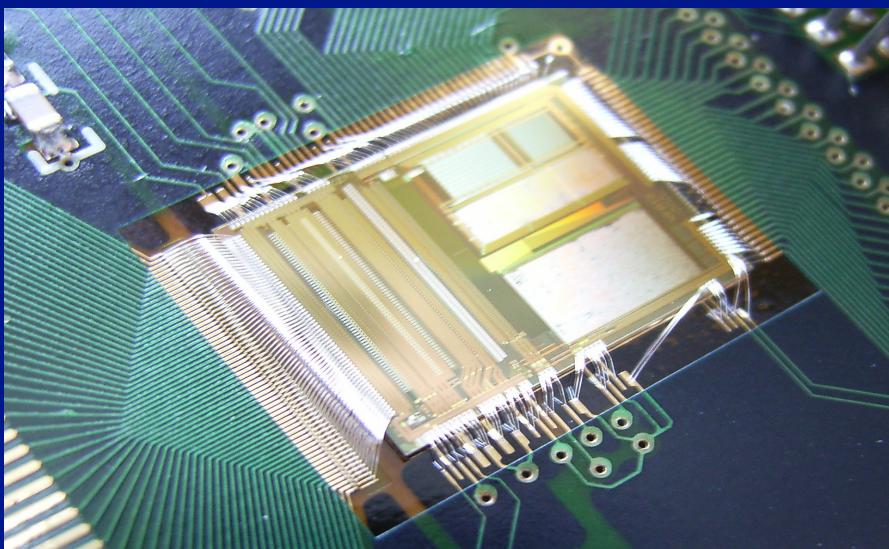
Using CERN
Projects
(GBTs & Vers)

Powering studies
CERN / UFL / Naples



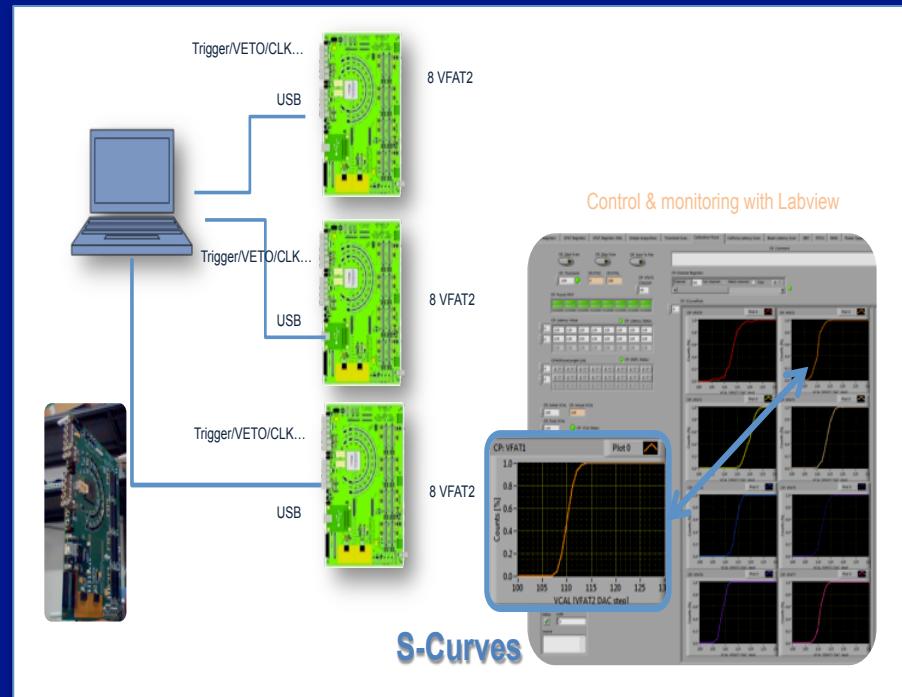
Front end Electronics

Existing- VFAT2 + Turbo



- Used in beam tests & lab characterisation.
- Provides triggering and tracking

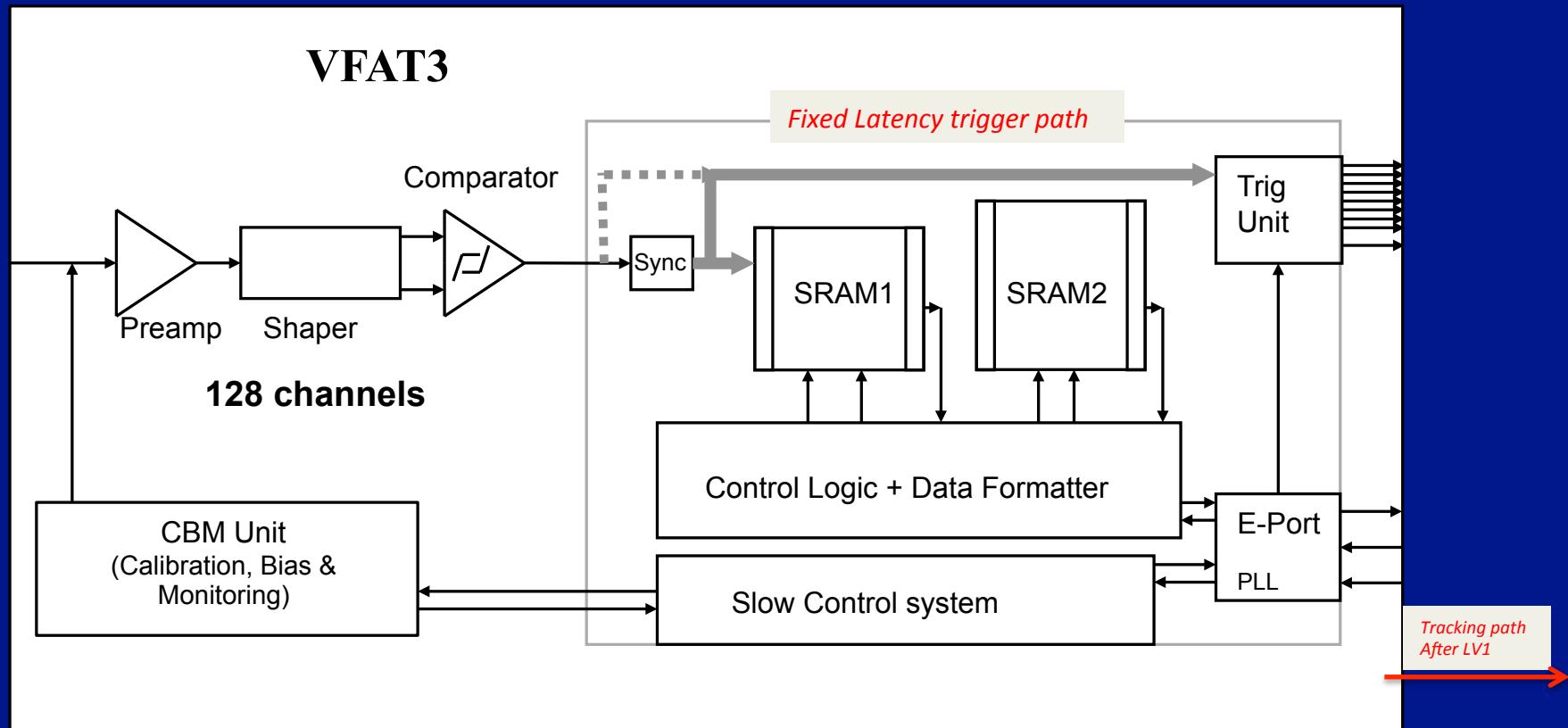
- Initial system
- VFAT2 (developed for TOTEM)
- Totem T2 Hybrids
- Turbo readout board (Sienna)



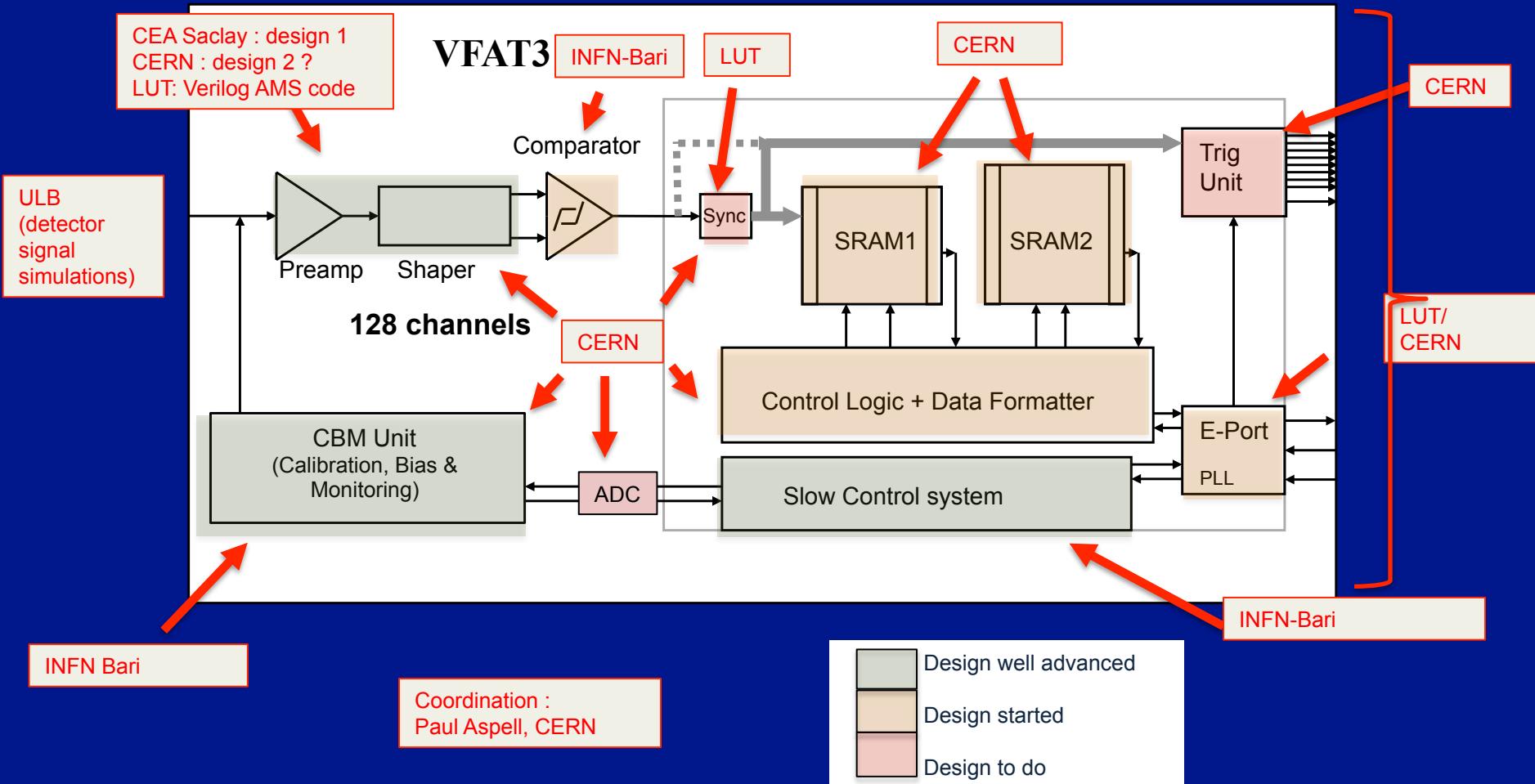
Main reasons to move from VFAT2 to VFAT3

- For both Trigger and Tracking we require binary hit data with channel location and time stamp accurate to one clock period.
 - VFAT2
 - Principle additional functionality required by new ASIC
 - Increased granularity at trigger level.
- Maximum trigger granularity = 16 channels
- Fixed shaping time = 25ns
- Data output rate limited to 40MHz.
- Max LV1 latency = 6.4us (CMS=3.2uS)
- Max LV1 rate = 200 kHz (CMS=100kHz)
 - Programmable shaping time, avoid ballistic deficit and improve S/N whilst maintaining timing resolution.
 - 320Mbps e-link for data output (compatible with GBT)
 - Max LV1 latency > 20us
 - Max LV1 rate > 1MHz

VFAT3



VFAT3 design institutes



Detector Studies & Timing Resolution

Timing resolution determined by detector.

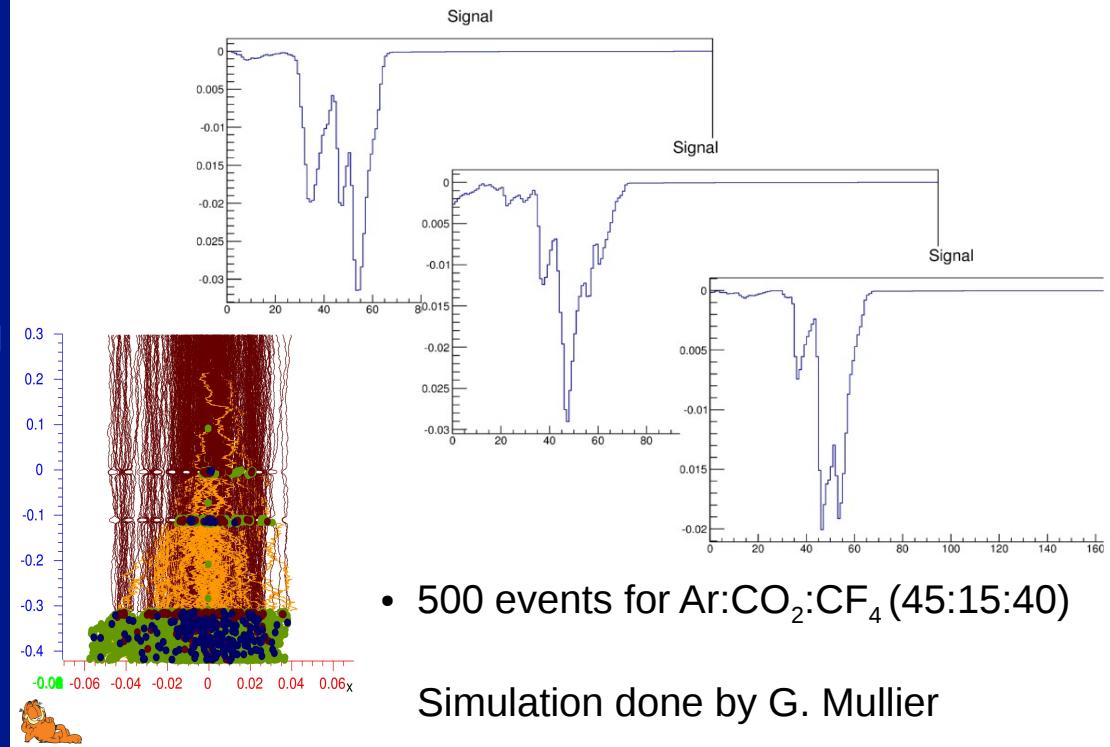
Fast shaping (as with VFAT2) give good timing resolution (<6ns) but bad signal to noise due to ballistic deficit.

Slower shaping times give better S/N but worse timing resolution due to time walk.

VFAT3 analog discriminator would use CFD or TOT to correct time walk and recover timing resolution.



GARFIELD simulations



2

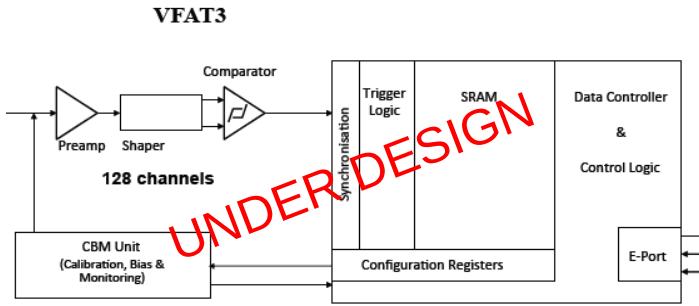
Combining detector charge with front-end

ULB

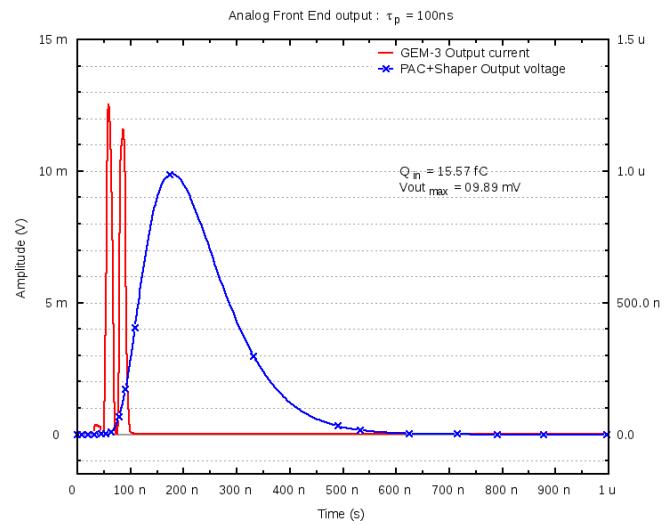
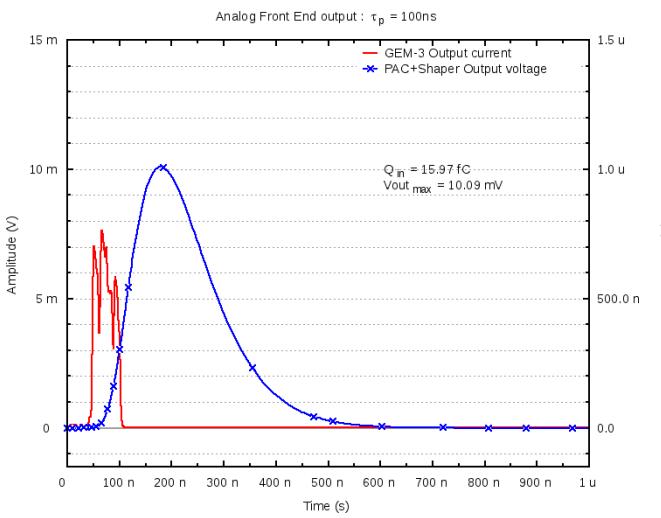
Electronics - VFAT3



Fabrice Guilloux



- “old” design :
 $F(t) = (t/\Tau)^n * \exp(-n*t/\Tau)$
 $n = 2$
 $\Tau = 20, 50, 100, 250, 500 \text{ ns}$
- “new” design :
 $F(t) = (t/\Tau)^n * \exp(-n*t/\Tau)$
 $n = 3$
 $\Tau = 1.1 * (25, 50, 75, 100, 200, 400 \text{ ns})$

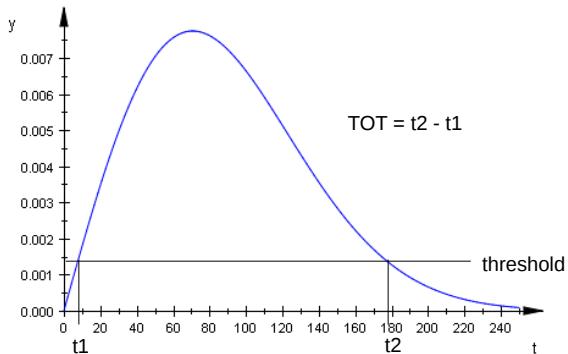


T.Maerschalk, ULB

Recovering Timing Resolution in VFAT3 TOT and CFD

ULB

Time Over Threshold (TOT)

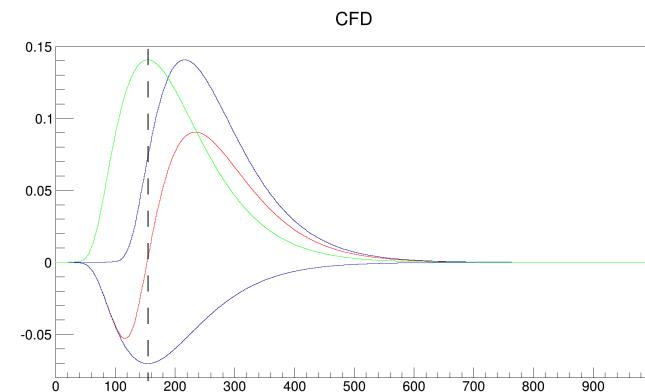


$\text{TOT} \rightarrow \# \text{ clock cycles} \rightarrow \text{Look Up Table (LUT)} \rightarrow T_1$
Compare T_1 from LUT to real T_1 of the signal

4

ULB

Constant Fraction Discriminator



The zero crossing and the signal maximum occur at the same time.

9

Comparison of TOT (Time Over Threshold) and CFD (Constant Fraction Discriminator) techniques:

Goal : Allow long shaping times to boost S/N by reducing ballistic deficit and at the same time retain good timing resolution.

TOT maintains timing resolution by correcting time walk through a LUT (look up table).

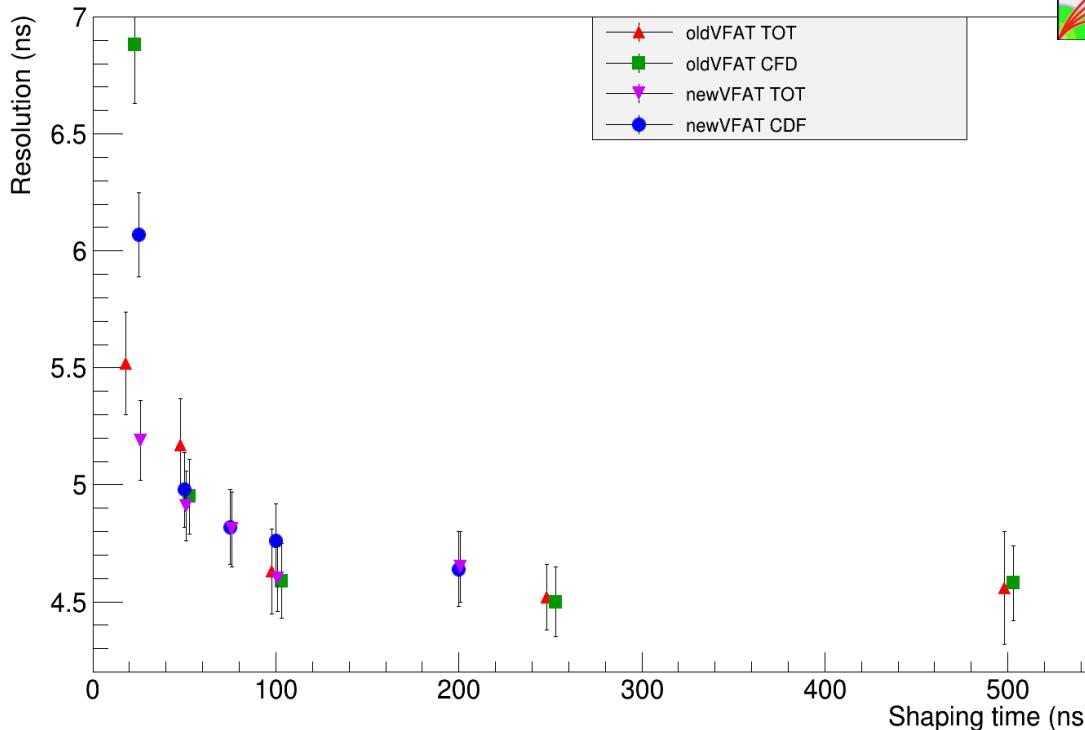
CFD corrects time walk internally in the comparator.

T.Maerschalk, ULB

Recovering Timing Resolution in VFAT3 TOT and CFD

ULB

all Time Resolutions Ar:CO₂:CF4



Old VFAT3

Shaping time (ns)	20	50	100	200	500
Resolution TOT (ns)	5.52 +/- 0.22	5.17 +/- 0.2	4.63 +/- 0.18	4.52 +/- 0.14	4.56 +/- 0.24
Resolution CFD (ns)	6.88 +/- 0.25	4.95 +/- 0.16	4.59 +/- 0.16	4.50 +/- 0.15	4.58 +/- 0.16

New VFAT3

Shaping time (ns)	25	50	75	100	200
Resolution TOT (ns)	5.19 +/- 0.17	4.91 +/- 0.15	4.81 +/- 0.16	4.60 +/- 0.14	4.65 +/- 0.15
Resolution CFD (ns)	6.07 +/- 0.18	4.98 +/- 0.16	4.82 +/- 0.16	4.76 +/- 0.16	4.64 +/- 0.16

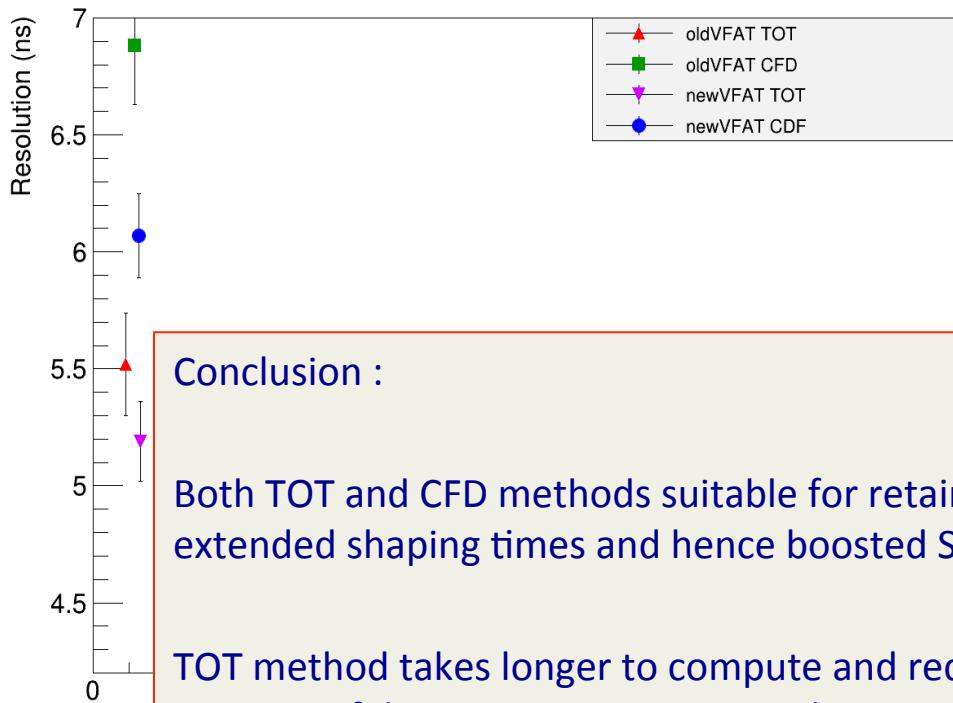
13

T.Maerschalk,
ULB

Recovering Timing Resolution in VFAT3 TOT and CFD

ULB

all Time Resolutions Ar:CO₂:CF4



Conclusion :

Both TOT and CFD methods suitable for retaining timing resolution with extended shaping times and hence boosted S/N.

TOT method takes longer to compute and requires a LUT – more expensive in terms of design resources required.

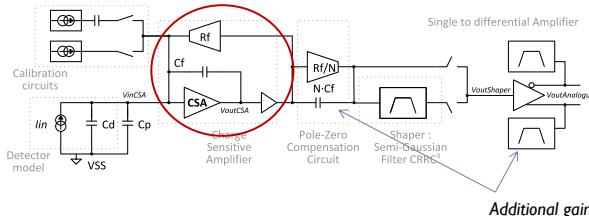
CFD is the most efficient in terms of design resources.

CFD chosen for VFAT3 design.

Old VFAT3		
Shaping time (ns)	20	
Resolution TOT (ns)	5.52	± 0.22
Resolution CFD (ns)	6.88	± 0.25
New VFAT3		
Shaping time (ns)	25	
Resolution TOT (ns)	5.19	± 0.17
Resolution CFD (ns)	6.07	± 0.18

Analog front-end

Front End electronics



Feedback capacitor

Cf	CSA Theoretical gain
100 fF	10 mV/fC
200 fF	5 mV/fC
400 fF	2.5 mV/fC
800 fF	1.25 mV/fC

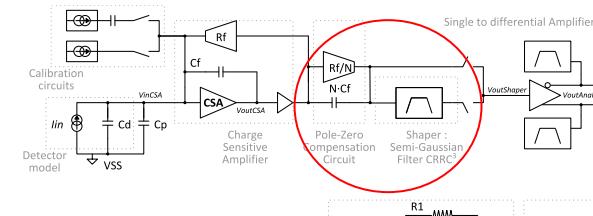
CSA

- Power consumption $\sim 800\mu\text{W}$ @ 1.5V
- 4 options for CFE. Typical performance with an ideal CRRC³ shaper :

CSA	Cdet	Tpeak	Phase margin	Gain	BW	GBW	Noise
1	30 pF	100 ns	90°	60 dB	1.8 MHz	816 MHz	918 e ⁻
2	30 pF	100 ns	85°	60 dB	2.4 MHz	786 MHz	764 e ⁻
3	30 pF	100 ns	78°	79.5 dB	0.3 MHz	787 MHz	840 e ⁻
4	30 pF	100 ns	85°	75 dB	0.3 MHz	807 MHz	1031 e ⁻

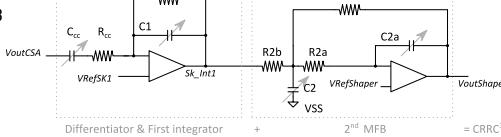
► 5 CMS GEM Electronics Physical Meeting 09/10/2013

Front End electronics



Shaper CRRC / CRRC² / CRRC³

- Programmable T_p
- Programmable DC output
- Power consumption : ~ 1.2 mW (programmable)



► 6 CMS GEM Electronics Physical Meeting 09/10/2013

09/10/2013

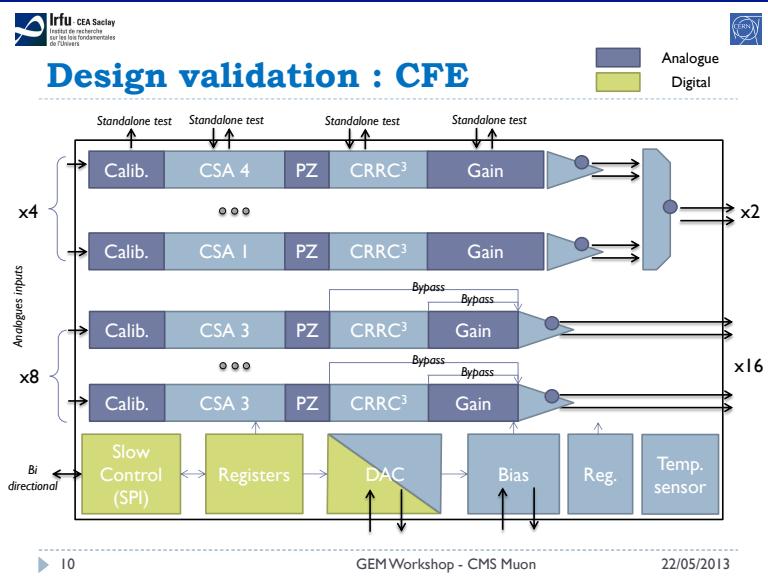
Key Parameter	Comment
detector charge polarity	Positive and Negative
Detectore capacitance range	5 - 80 pF
Peaking Times (Tp)	25, 50, 75, 100, 200 ns
Programmable gain	1.25 to 50 mV/fC
Max Dynamic Range (DR)	Up to 200 fC
Linearity	< 1% of DR
Power Consumption	2mW/ch
Power Supply	1.5V
ENC	$\approx 1100e$ (with $T_p = 100\text{ns}$, $C_d = 30\text{pF}$)
Technology	IBM 130nm

F. Guilloux, CEA Saclay

FE & CFD test chips



Design validation : CFE

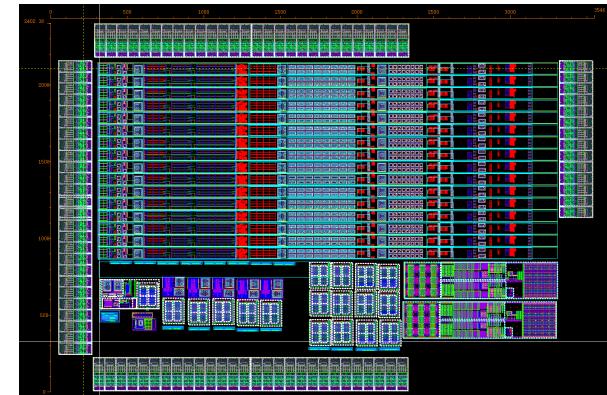


F. Guilloux,
CEA Saclay



Design validation : CFE

Floorplan



CMS GEM Electronics Physical Meeting

09/10/2013

FE and CFD test chips planned for May 2014 submission

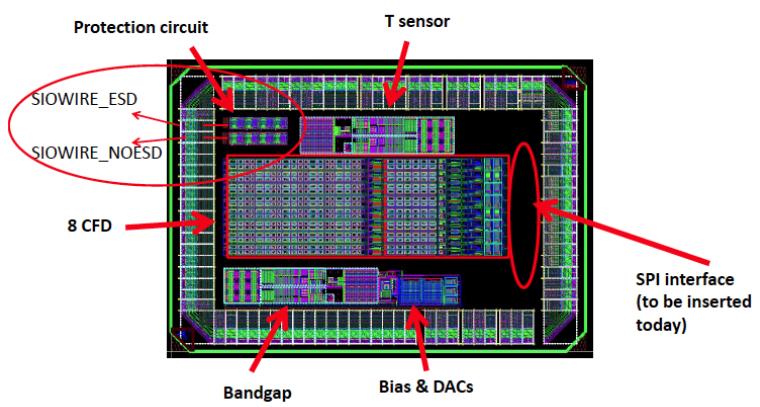
F. Loddo, C.Tamma , INFN Bari



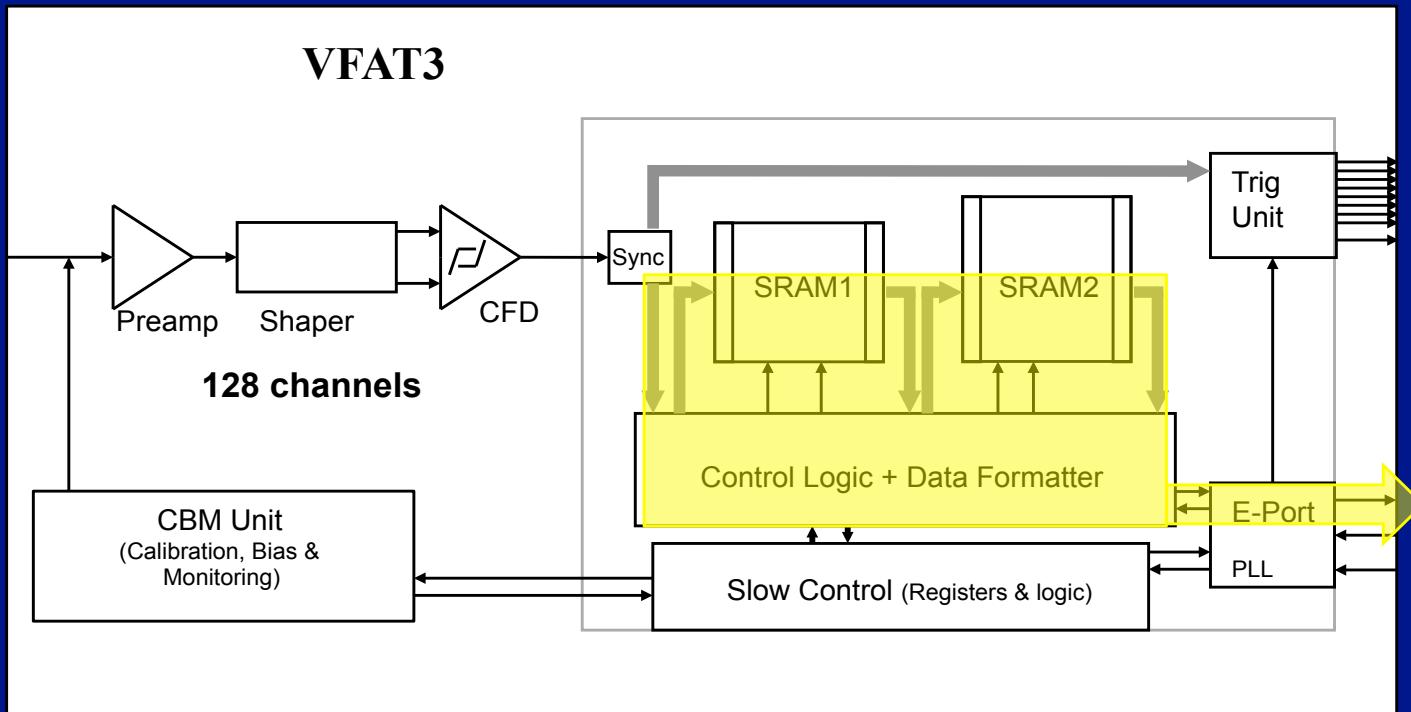
VFAT3-CFD chip preparation

- Submission date: 19 May 2014
- Budget: 15 kEuro → ~ 5 mm²

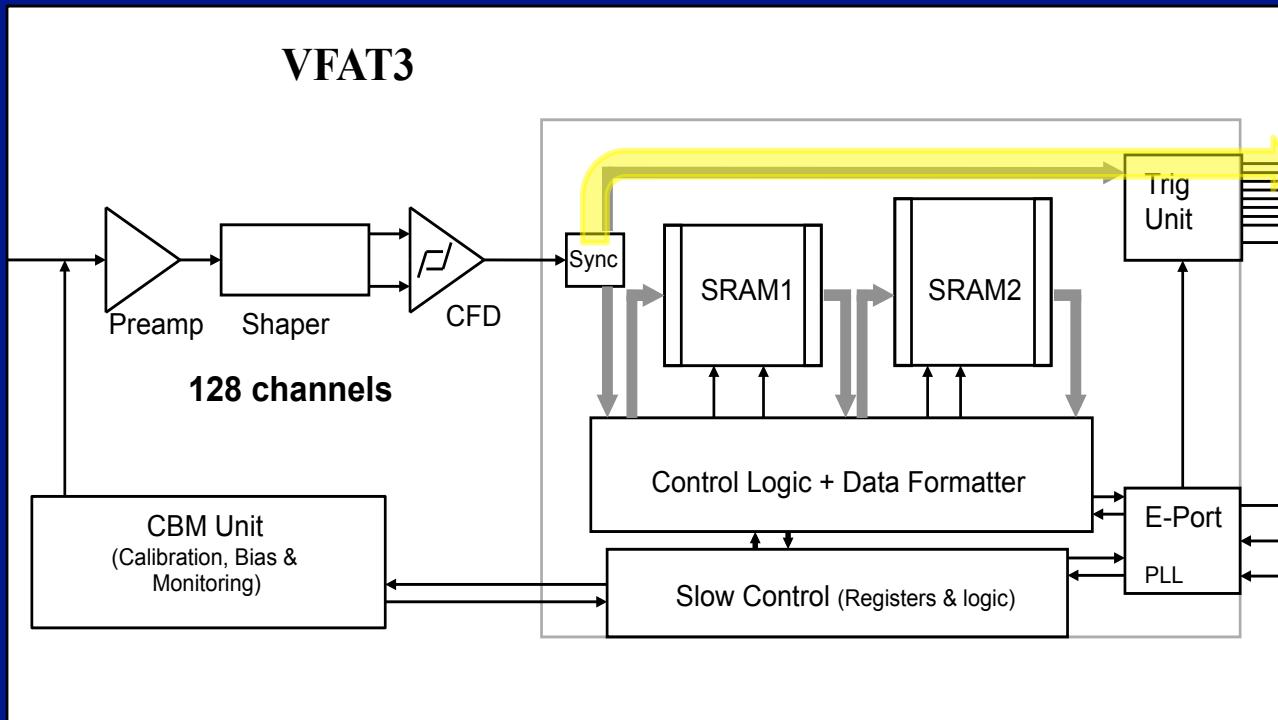
Floorplan: 2.7 x 1.85 mm²



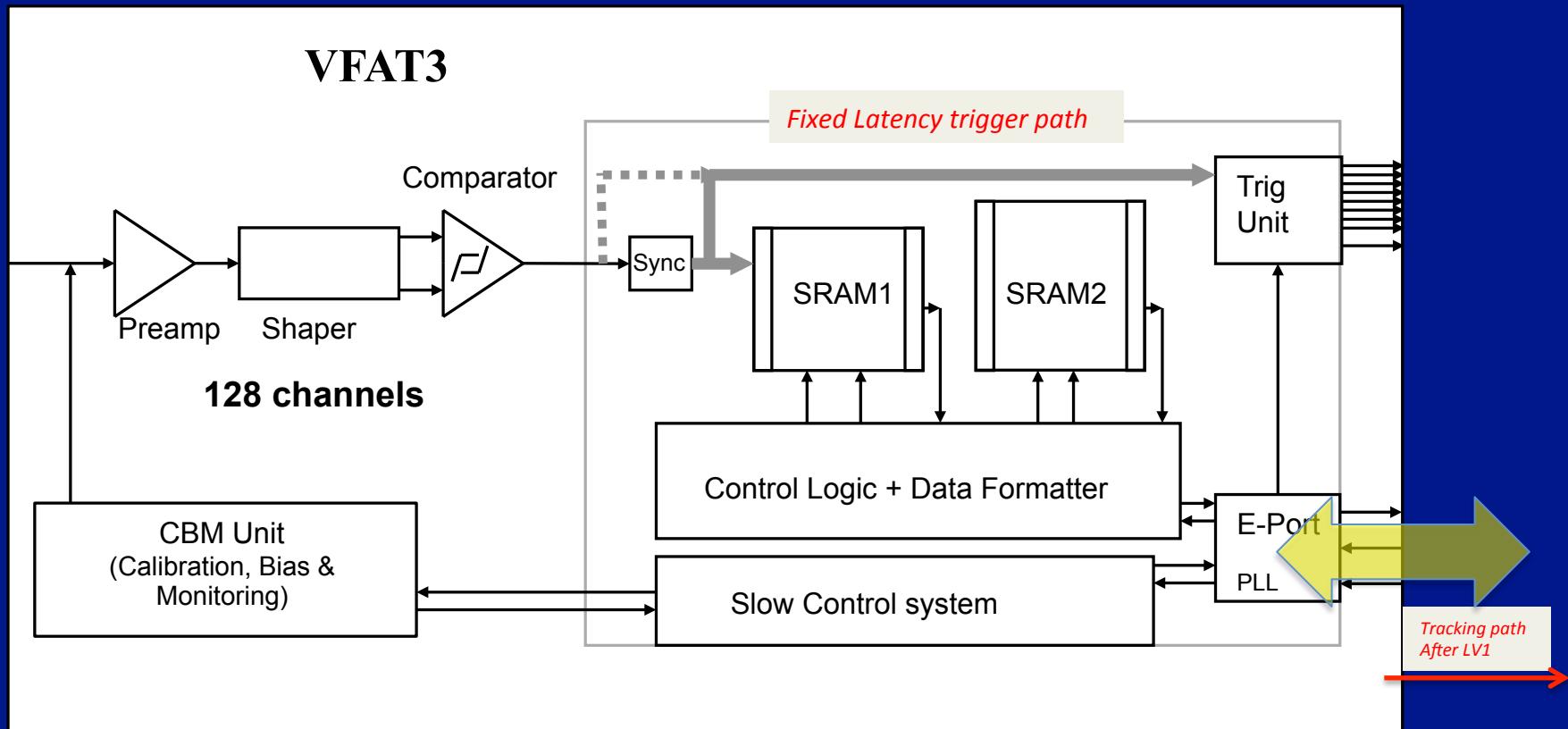
The Variable Latency Data Path



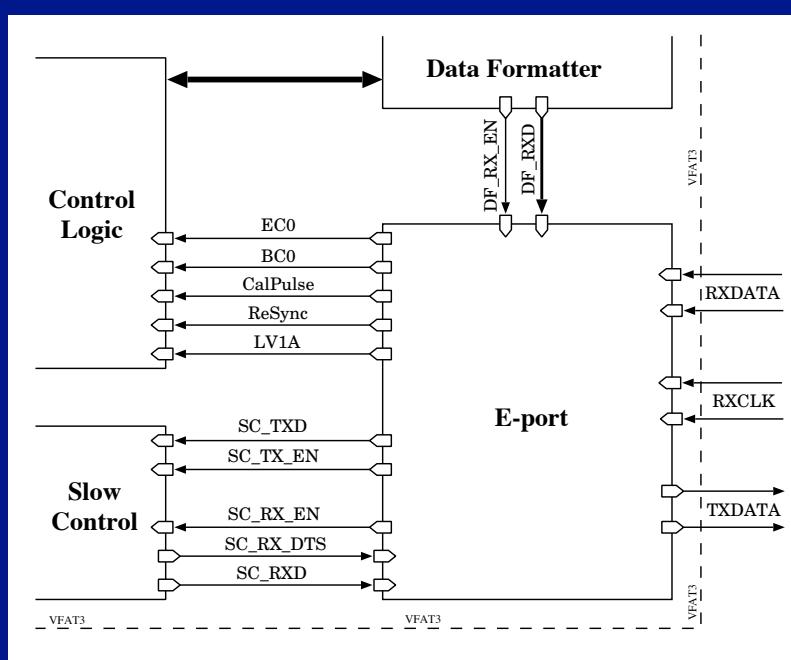
The Fixed Latency Trigger Path



VFAT3 Communication



E-Port



All communication with VFAT3 passes through the E-port.
The functions provided by the E-Port include :

Synchronisation (40MHz) & phase adjustment

Reception of Control Commands via Control Codes

Reception of Slow Control commands via Control Codes (SC0, SC1), (*I^pbus wrapped in HDLC*)

Transmission of data packets

Transmission of Slow Control data packets

Transmission of Error warnings

8 bit Control codes.
Each code is allocated a dedicated function

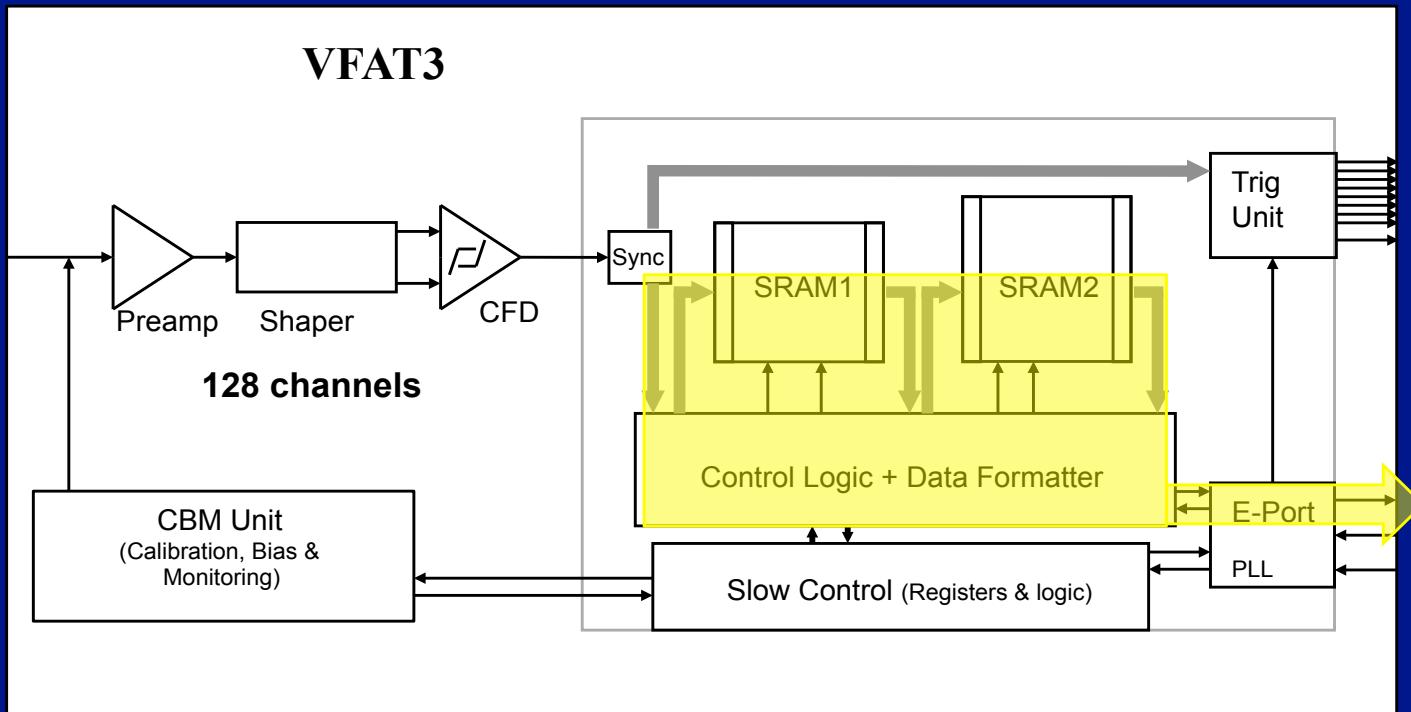
Name	4-bit word	8-bit representations	Disp.
A	0000	XXXXXXXX	0
B	0001	XXXXXXX0	0
C	0010	XXXXXXX1	0
D	0011	XXXXXXX0	0
E	0100	XXXXXXX0	0
F	0101	XXXXXXX0	0
G	0110	XXXXXXX0	0
H	0111	XXXXXXX0	0
I	1000	XXXXXXX0	0
J	1001	XXXXXXX0	0
K	1010	XXXXXXX0	0
L	1011	XXXXXXX0	0
M	1100	XXXXXXX0	0
N	1101	XXXXXXX0	0
O	1110	XXXXXXX0	0
P	1111	XXXXXXX0	0

FSCC	Character	Description
EC0	A	Reset the Event Counter.
BC0	B	Reset the Bunch-Crossing-Zero Counter.
CalPulse	C	Injection of CalPulse.
ReSync	D	Resets all state machines in CL and DF.
SCOnly	E	Force "Slow Control Only" Mode.
Run Mode	F	Return from "Slow Control Only" Mode.
LV1A	G	First Level Trigger.
SC0	H	Sends "0" to the Slow Control.
SC1	I	Sends "1" to the Slow Control.

M. Dabrowski (CERN)

Slow Control : G.DeRobertis (INFN Bari)

The Variable Latency Data Path



Data packet path



Online:

VFAT3 DP should contain minimum amount of data possible to optimise bandwidth.

Can be zero suppressed or not

Offline :

DAQ DP must contain all information relating to :

Chip ID (location within the whole detector)
Event number
Channels hit.

Note on zero suppression:

If VFAT3 DP contains zero suppression then packets will arrive at the uTCA “out of order” with respect to other VFATs in the system however they will remain consecutive for each individual VFAT.

VFAT3 has 2 different options for the Data Packet “Lossless” and “SPZPS”

Data Packets : Lossless & SPZS

Single Time Slot Per Event (if TSPE register is equal to 00)

Data Packets				Sequential Partial Zero Suppression			Relevant registers		
Lossless			Registers			Registers		Registers	
Registers	Data Packet	No. Bits	Comment	DT	SZP	SZD	DT	SZP	Size(EC)
0 0 0	Header I	8	Basic data packet	1	0	0	Header I	8	Basic SPZS data packet
	EC+BC / EC / BC	8 - 48	Size depends on TT, Ecb, BCb				EC+BC / EC / BC	8 - 48	Size depends on Partitions/P16
	Data	128					Data	16 - 96	
	CRC	16					CRC	16	
0 0 1	Header I	8	Basic data packet	1	0	1	Header I	8	Basic SPZS data packet
	EC+BC / EC / BC	8 - 48	Size depends on TT, Ecb, BCb				EC+BC / EC / BC	8 - 48	Size depends on TT, Ecb, BCb
	Data	128					Data	16 - 96	Size depends on Partitions/P16
	CRC	16					CRC	16	
	Header II	8	Zero Suppressed				Header II	8	Zero Suppressed
	EC	8 - 24	Size depends on Ecb				EC	8 - 24	Size depends on Ecb
	CRC	16					CRC	16	
0 1 x	Header I	8	Basic data packet	1	1	x	Header I	8	Basic SPZS data packet
	EC+BC / EC / BC	8 - 48	Size depends on TT, Ecb, BCb				EC+BC / EC / BC	8 - 48	Size depends on TT, Ecb, BCb
	Data	128					Data	16 - 96	Size depends on Partitions/P16
	CRC	16					CRC	16	
	Header II	8	Zero Suppressed				Header II	8	Zero Suppressed
M. Dabrowski (CERN)							P16	Comment	
							0	Send numbers of partitions according to Partitions register	
							1	Send only high level information (16bit)	

Highly programmable to optimise the data packet content depending on occupancy and trigger rate.

Multiple time slots per event can be obtained by the DAQ sending multiple successive VFAT triggers per one CMS LV1A accept. House keeping in the DAQ would be needed to keep track of VFAT3 EC values and the real CMS EC values.

“Sequential” Partition Zero Suppression (SPZS) (a variation on the CMS RPC data format)

SPZS Data Field

0 partitions hit

Partition 1	0
Partition 2	0
Partition 3	0
Partition 4	0
Partition 5	0
Partition 6	0
Partition 7	0
Partition 8	0



Partition 16	0
--------------	---

Data Field = 16b

1 partition hit

Partition 1	0
Partition 2	0
Partition 3	0
Partition 4	1
Data	8 bit data
Partition 5	0
Partition 6	0
Partition 7	0
Partition 8	0



Partition 16	0
--------------	---

Data Field = 24b

2 partitions hit

Partition 1	0
Partition 2	0
Partition 3	0
Partition 4	1
Data	8 bit data
Partition 5	0
Partition 6	1
Data	8 bit data
Partition 7	0
Partition 8	0



Partition 16	0
--------------	---

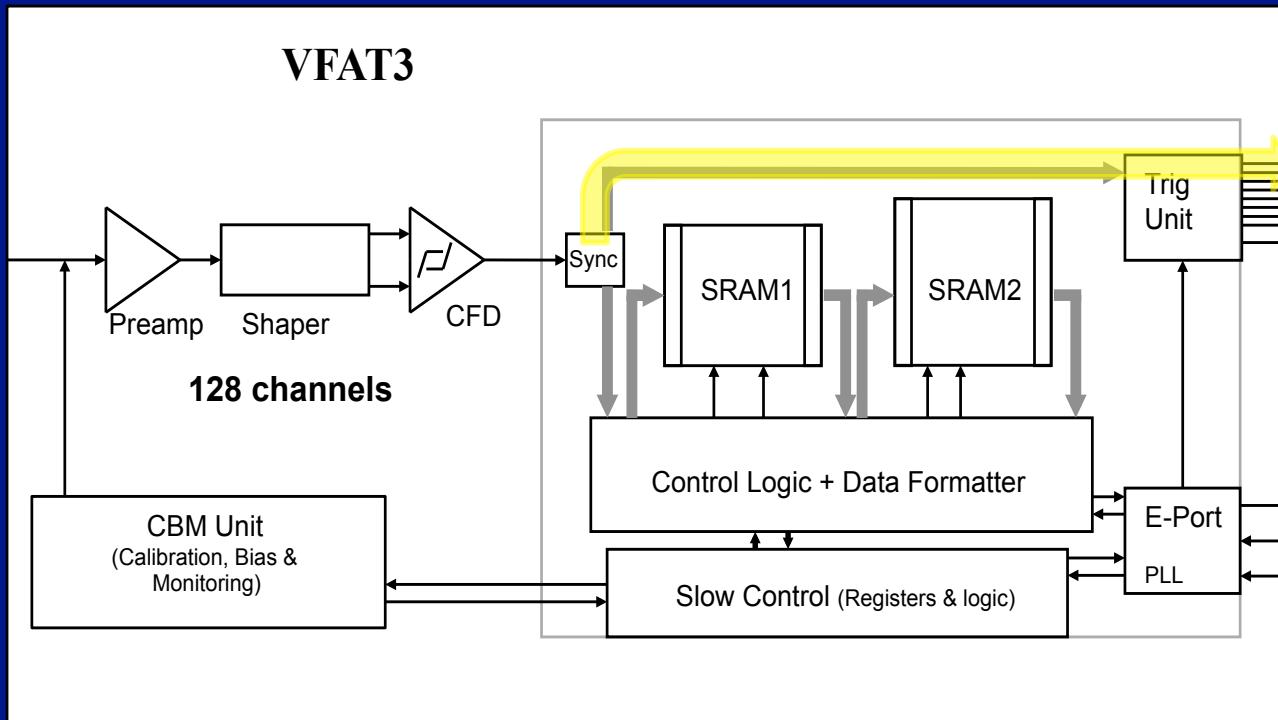
Data Field = 32b

16 Partitions, 8 channels / partition

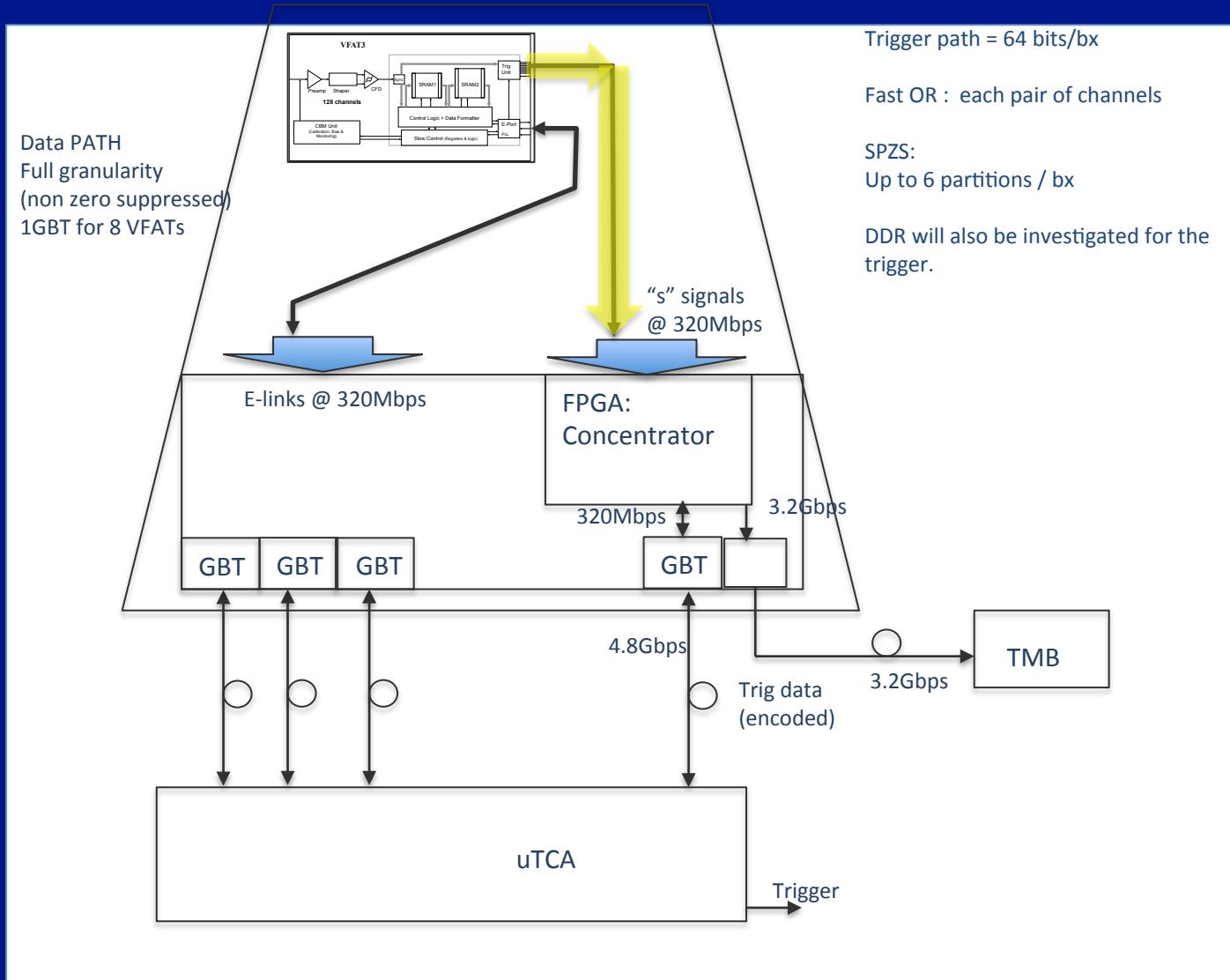
16 bits total for partition identification

8 bits per partition

The Fixed Latency Trigger Path



Trigger Path Data options



VFAT3 Submission Schedule & Goals

VFAT3 steps in yearly quarters

Q1 2015	Submission of VFAT3 in IBM130nm	↓	Design of characterisation boards
Q2 2015	Return of VFAT3 from foundry		VFAT3(a) Chip test & characterisation
Q3 2015	Ist test results		VFAT3(b) design work
Q4 2015	Release of VFAT3(a) if possible.		
Q1 2016	2 nd Submission of VFAT3(b) if necessary		VFAT3(a) radiation qualification P3 Cosmic stand & test beam Development
Q2 2016	Return of VFAT3b from foundry		
Q3 2016	Ist test results (b)		
Q4 2016	Release of VFAT3(b)		

Schedule risk factors:

Process: IBM 130nm. We are considering moving the design to TSMC 130nm or 65nm in which case the schedule would be affected.
Manpower : The chip is being designed largely by short term students. Relies on their contracts being extended.

Thanks